

For Immediate Release

TAIYO YUDEN Adds High-Performance *Bluetooth*[®] Smart Modules

Expands the Lineup in Response to Diversifying IoT-Related Devices

TOKYO, March 31, 2016—TAIYO YUDEN CO., LTD. announces the launch of *Bluetooth*^{®*1} Smart^{*2} modules EYSHCNZXZ (9.6 x 12.9 x 2.0 mm) and EYSHJNZXZ (5.1 x 11.3 x 1.3 mm).

These wireless communication modules, compatible with the wireless communication standard *Bluetooth*[®] v4.2 low energy (*Bluetooth*[®] Smart), are ideal for various small, thin devices including healthcare equipment, wearable devices, smartphone peripherals, as well as IoT-related devices.

In response to diverse customer needs, TAIYO YUDEN has launched compact products as well as products with our original embedded software. These new products launched today offer greater functionality yet in the same geometries as our existing products. A high-performance CPU and large-capacity memory are embedded to deal with more complicated applications.

These Products will be prepared in Japan in April 2016, at a production rate of two million units per month. EYSHCNZXZ will commence in April 2016, and EYSHJNZXZ will also commence by the first half of 2016 fiscal year. The sample price for both products is 3,000 yen per unit.^{*3}

Technology Background

Bluetooth[®] Smart, which is part of the *Bluetooth*[®] standards, is a very low-energy communication standard, and so the technology is increasingly being adopted in many different devices, including healthcare products such as bathroom scales and blood-pressure meters, as well as wearable devices such as activity trackers. In addition, the emergence of various services based on a function of *Bluetooth*[®] Smart known as "beacon" is resulting in a rapid increase in the number of *Bluetooth*[®] Smart-enabled devices. As a result, an increasing variety of individual devices and customer needs have made it necessary to offer additional products in the *Bluetooth*[®] Smart module lineup.

In response to this demand, TAIYO YUDEN has launched EYSHCNZXZ and EYSHJNZXZ in addition to its current product lineup. These products feature a high-performance ARM[®] Cortex[®]-M4 processor^{*4} with floating-point unit and twice the memory capacity of existing products, yet with the same geometries. We have expanded the product lineup to deal with not only IoT, but also diverse services as well as complicated, sophisticated applications.

TAIYO YUDEN is committed to extending its lineup of products that offer high reliability, compactness, and a lower profile to meet market needs.

These products will be published on the solution proposal webpage for [Bluetooth[®] Smart](#) technology on our website together with existing products. The webpage also features a selection chart that allows customers to select the optimum modules for their needs.



Expand business opportunities and accelerate time to market by choosing TAIYO YUDEN's *Bluetooth*[®] Smart modules.

*1 The *Bluetooth*[®] word mark and logos are owned by Bluetooth SIG, Inc. and the use of such marks by TAIYO YUDEN CO., LTD. is under license.

*2 "*Bluetooth*[®] Smart" is a standard stipulated by Bluetooth SIG, Inc.

*3 The sample price mentioned in this release is our direct sales price. When considering purchasing via a sales agency, please contact the agency for the sample price.

*4 ARM and Cortex are registered trademarks of ARM Limited (or its subsidiaries) in the EU and other countries. All rights reserved.

■ Applications

Wireless communication modules for a variety of small, thin devices including healthcare equipment, wearable devices, and smartphone peripherals.

The characteristics of the new *Bluetooth*[®] Smart modules are as shown below.

| Part Number | Size (L x W x H) | Specification | I/F | RAM (kB) | Certification | Temperature |
|-------------|------------------------|----------------------------|-------------------------|-------------|---------------------------|-----------------|
| EYSHCNZZ | 9.6 x 12.9 x 2.0 mm | V4.2 BLE | UART | 64 | Japan FCC IC CE* | -25 to +75°C |
| EYSHJNZXZ | 5.1 x 11.3 x 1.3 mm | Single Slave/ Master | SPI I ² C | | | |

* The CE test report can be provided.